221 ■ Install stand-to-attachment boss after final wash. Torq shall be 5 pi lbin. Torq shall be per the Label Table in the PDF schematic.
222 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
223 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
224 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

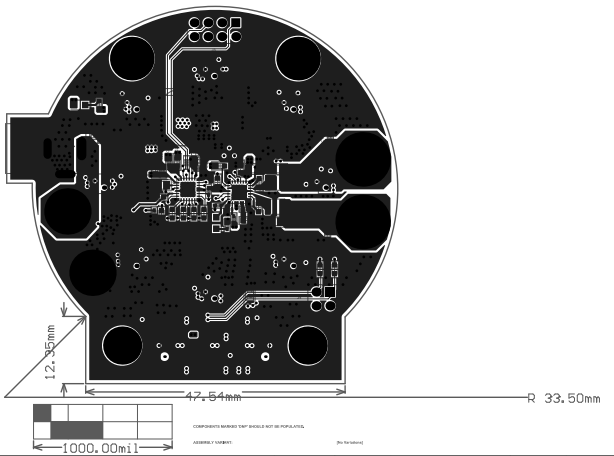
STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.
2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.
3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED .
PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA
TENTING / COVERING " REQUIREMENTS.
4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE
WITH COPPER. SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.

DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.685 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = [redacted]Bottom
PLOT NAME = L1_TOP
BOARD #: Robotics Design REV: A SVN REV: Not in version control
TID #: TIDA-060054
GENERATED : 10/26/2026 9:53:31 PM
TEXAS INSTRUMENTS

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ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

221 ■ Board sized to silkscreened size after final mask. Test shall be 0 at here. Test shall be per the Label Table in the PDF schematic.
222 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
223 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
224 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

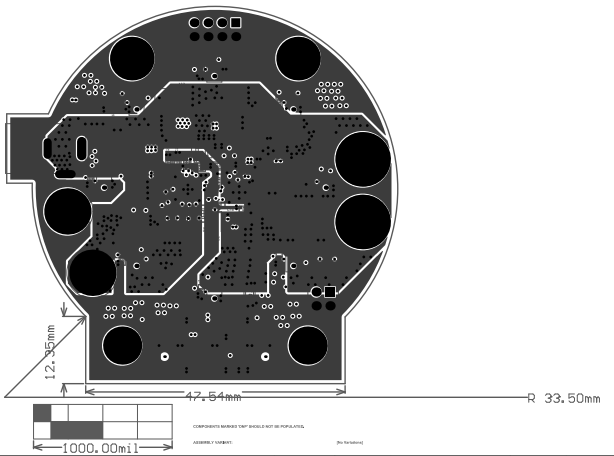
STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.
2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.
3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED .
PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA
TENTING / COVERING " REQUIREMENTS.
4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE
WITH COPPER. SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

JUSTIFICATION FOR TOP CLOCKS "PAD" DOMAIN OVERSPOKED

(overlaid with all) TRANSKEY SUBMISSION

DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.685 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = [redacted]Bottom
PLOT NAME = L2-GND1
BOARD #: Robotics Design REV: A SVN REV: Not in version control
DID #: TIDA-060054
GENERATED : 10/26/2026 9:53:32 PM TEXAS INSTRUMENTS

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ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

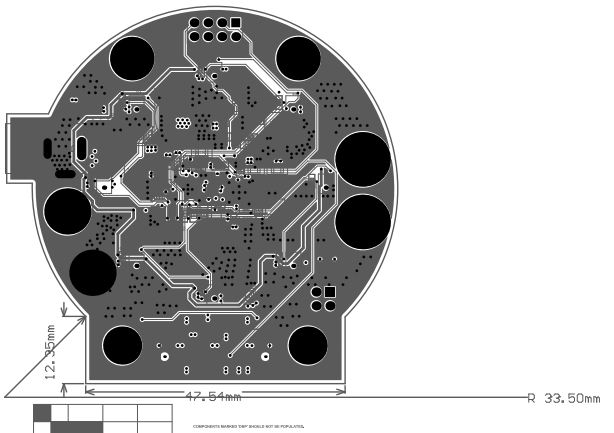
FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.

2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.

3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED .
PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA
TENTING / COVERING " REQUIREMENTS.

4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE
WITH COPPER. SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.685 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = [redacted]Bottom
PLOT NAME = L3_Signal

BOARD #: Robotics Design REV: A SVN REV: Not in version control
TID #: TIDA-060054
GENERATED : 10/26/2026 9:53:24 PM
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221 ■ Board sized to silkscreened box after final mask. Test shall be 0 pt box. Test shall be per the Label Table in the PDF schematic.

222 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

223 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

224 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

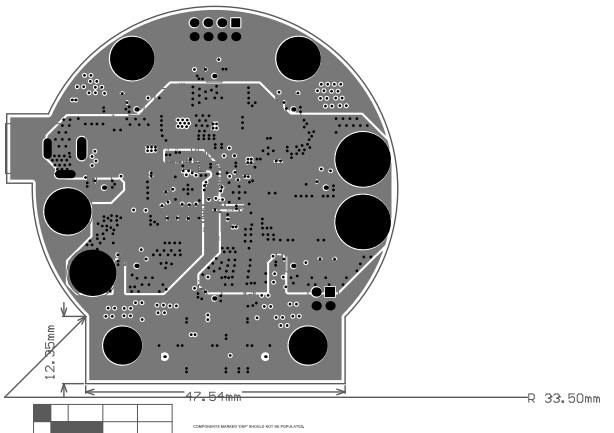
FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.

2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.

3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED .
PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA
TENTING / COVERING " REQUIREMENTS.

4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE
WITH COPPER. SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

SOLUTION DB TOP CLOCKS *PRE-SEMIAM ETCHBOARD

[unselected-off] TRANSKY SUBSTRATE

DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.685 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = [redacted]Bottom
PLOT NAME = L4_GND2

BOARD #: Robotics Design REV: A SVN REV: Not in version control
BID #: TIDA-060054
GENERATED : 10/26/2026 3:53:35 PM
TEXAS INSTRUMENTS

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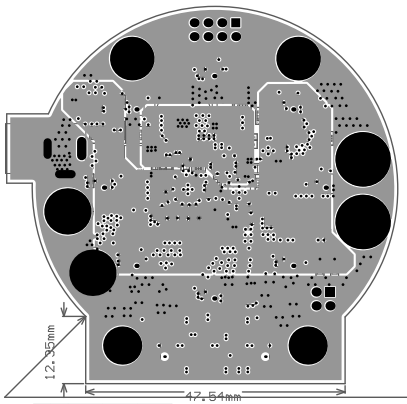
ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

221 Board sized to silkscreened box after final mask. Test shall be 0 pt here. Test shall be per the Label Table in the PDF schematic.

222 These assemblies are ESD sensitive, ESD precautions shall be observed.

223 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

224 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

JUSTIFICATION TOP CUSTOMIZE "PAD" DOMAIN OVERWRITTEN

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.

2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.

3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1) AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED . PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA TENTING / COVERING " REQUIREMENTS.

4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE WITH COPPER. SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES . MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.

DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.685 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = [redacted]Bottom
PLOT NAME = L6_PWR
BOARD #: Robotics Design REV: A SVN REV: Not in version control
SID #: TIDA-060054
GENERATED : 10/26/2026 9:53:26 PM
TEXAS INSTRUMENTS

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ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

221 ■ Board sized to silkscreened lines after final route. Test shall be 5 pt here. Test shall be per the Label Table in the PDF schematic.
222 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
223 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
224 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

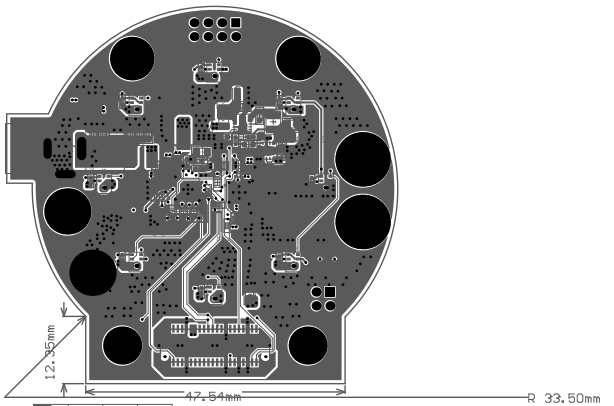
STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.
2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.
3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED .
PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA
TENTING / COVERING " REQUIREMENTS.
4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY+RESIN AND OVERPLATE
WITH COPPER, SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.685 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = [redacted]Bottom
PLOT NAME = L6_Bottom
BOARD #: Robotics Design REV: A SVN REV: Not in version control
STD #: TIDA-060054
GENERATED : 10/26/2026 9:53:37 PM
TEXAS INSTRUMENTS

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ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

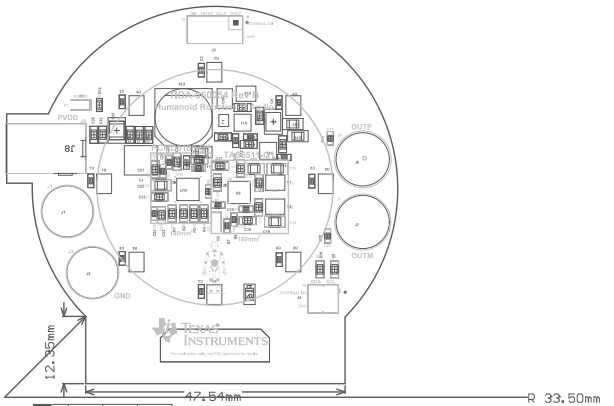
STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.
2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.
3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED .
PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA
TENTING / COVERING " REQUIREMENTS.
4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE
WITH COPPER, SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.685 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = [illegible] Bottom
PLOT NAME = Top Silkscreen Overlay

BOARD #: Robotics Design REV: A SVN REV: Not in version control
SID #: TIDA-060054
GENERATED : 10/26/2026 9:53:29 PM
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ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

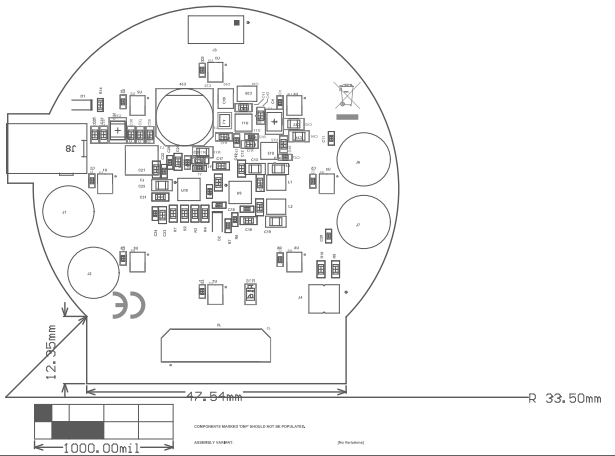
STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.
2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.
3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED .
PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA
TENTING / COVERING " REQUIREMENTS.
4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE
WITH COPPER. SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.685 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = Bottom
PLOT NAME = Bottom Silkscreen Overlay

BOARD #: Robotics Design REV: A SVN REV: Not in version control
TID #: TIDA-060054
GENERATED : 10/26/2026 9:53:40 PM
TEXAS INSTRUMENTS

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ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

221 ■ Install shield to silkscreened box after final wash. Test shall be 5 pt box. Test shall be per the Label Table in the PDF schematic.
222 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
223 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
224 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
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3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.
2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.
3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
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4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE
WITH COPPER. SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.

DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.685 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = [illegible]Bottom
PLOT NAME = Top Paste,Mask Prim
BOARD #: Robotics Design REV: A SVN REV: Not in version control
TID #: TIDA-060054
GENERATED : 10/26/2026 9:53:41 PM
TEXAS INSTRUMENTS

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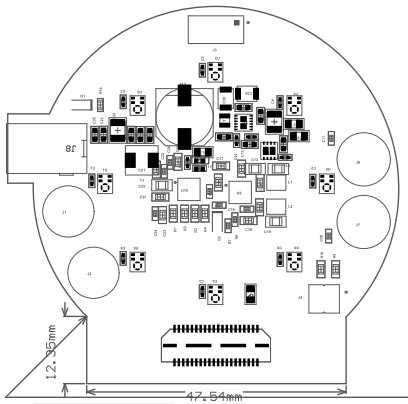
ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

221 Board sized to silkscreened box after final route. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

222 These assemblies are ESD sensitive, ESD precautions shall be observed.

223 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

224 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

JUSTIFICATION FOR TOP CLOCKS "PKE" DOMAIN ENTERPRISED

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.

2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.

3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED .
PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA
TENTING / COVERING " REQUIREMENTS.

4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE
WITH COPPER, SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.

DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.685 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM- TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = Bottom
PLOT NAME = Bottom Paste Mask Print

BOARD #: Robotics Design REV: A SVN REV: Not in version control
3RD MOTTO MOFI GROUP BOM
3D #: TIDA-060054
GENERATED : 10/26/2026 9:53:42 PM
TEXAS INSTRUMENTS

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ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

221 Bevel sized to silkscreened text after final mask. Text shall be 5 pt font. Text shall be per the Label Table in the PDF schematic.

222 These assemblies are ESD sensitive, ESD precautions shall be observed.

223 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

224 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

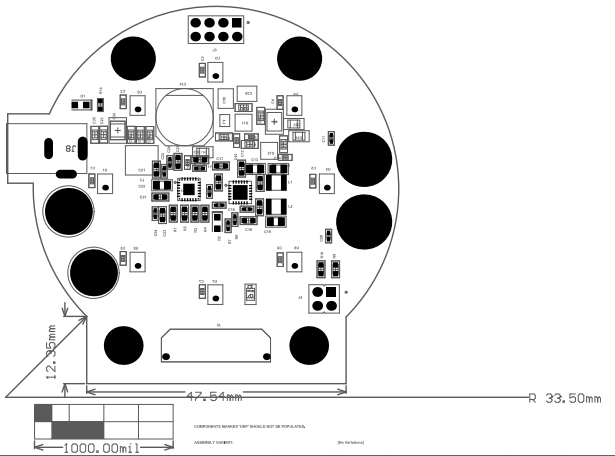
FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.

2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.

3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED .
PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA
TENTING / COVERING " REQUIREMENTS.

4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE
WITH COPPER. SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

SOLDERMASK SHALL BE TENTED OVER EXPOSED VIAS

DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.685 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = Top Solder Mask Print
PLOT NAME = Top Solder Mask Print

BOARD #: Robotics Design REV: A SVN REV: Not in version control
TID #: TIDA-060054
GENERATED : 10/26/2026 9:53:44 PM
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ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

221 Bevel sized to silkscreened text after final mask. Text shall be 5 pt font. Text shall be per the Label Table in the PDF schematic.

222 These assemblies are ESD sensitive, ESD precautions shall be observed.

223 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

224 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

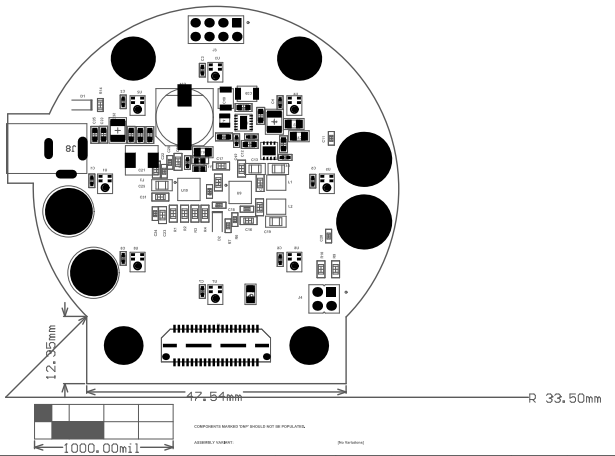
FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.

2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.

3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1) AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED . PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA TENTING / COVERING " REQUIREMENTS.

4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE WITH COPPER, SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES . MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

JUSTIFICATION FOR TOP CLOCKS "NOT CLEAN AS STENCILED"

DESIGN INFORMATION			
MIN. TRACK WIDTH:	5 MIL		
MIN. CLEARANCE:	6 MIL		
MIN. VIA PAD SIZE:	19.685 MIL		
MINIMUM ANNULAR RING	0.05mm (2MIL)	EXTERNAL	
PER	IPC-D-275 CLASS 2 LEVEL C		
REGISTRATION TOLERANCES:	METAL +/- 5 MIL, HOLES	+/- 3 MIL	
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED):		+/- 3 MIL	

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = Bottom
PLOT NAME = Bottom Solder Mask Print

BOARD #: Robotics_Design REV: A SVN REV: Not in version control
3RD NOTED NOT EPOXY R/H
3D #: TIDA-060054
GENERATED : 10/26/2026 9:53:45 PM
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ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

221 ■ Board sized to silkscreened box after final route. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

222 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

223 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

224 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

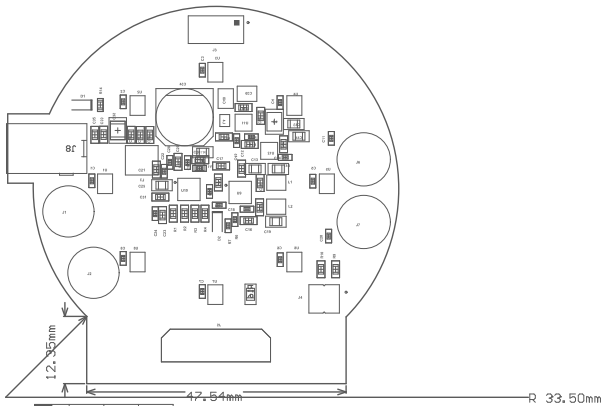
FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.

2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.

3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED .
PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA
TENTING / COVERING " REQUIREMENTS.

4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE
WITH COPPER, SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

JUSTIFICATION FOR TOP CLOCKS "PAD" DESIGNATION PERFORMED

DESIGN INFORMATION			
MIN. TRACK WIDTH:	5 MIL		
MIN. CLEARANCE:	6 MIL		
MIN. VIA PAD SIZE:	19.685 MIL		
MINIMUM ANNULAR RING	0.05mm (2MIL)	EXTERNAL	
PER	IPC-D-275 CLASS 2 LEVEL C		
REGISTRATION TOLERANCES:	METAL +/- 5 MIL, HOLES	+/- 3 MIL	
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED):		+/- 3 MIL	

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design

DESIGNED FOR: TI Internal

FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE

LAYER NAME = [redacted]Bottom

PLOT NAME = M1 Board Outline

BOARD #: Robotics Design REV: A SVN REV: Not in version control

IID #: TIDA-060054

GENERATED : 10/26/2026 9:53:46 PM

TEXAS INSTRUMENTS

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ENGINEER: Garret Godfrey

LAYOUT BY: Tessolve

SCALE: 0.72

ALTIUM DESIGNER VERSION: 23.1.1.15

221 ■ Install shield to silkscreened box after final wash. Test shall be 5 pt box. Test shall be per the Label Table in the PDF schematic.

222 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

223 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

224 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

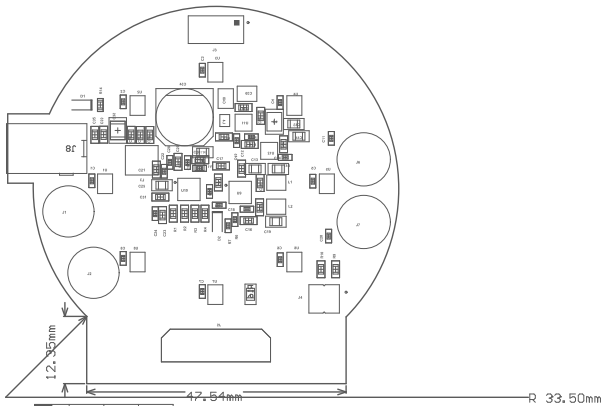
FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.

2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.

3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1) AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED . PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA TENTING / COVERING " REQUIREMENTS.

4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE WITH COPPER, SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES . MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

SOLDERMASK SHALL BE TOP CLOSURE "PRE-SOLDER ETCHED" [selected ref]

TRANSPARENT SOLDERMASK

DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL

MIN. CLEARANCE: 6 MIL

MIN. VIA PAD SIZE: 19.685 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

[X] FR-4 [ ] FR-4 High Tg [ ] OTHER

THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up

TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:

REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES

PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:

SILKSCREEN: [X] TOP [X] BOTTOM

SILKSCREEN COLOR: [X] WHITE [ ] OTHER

SOLDER RESIST COLOR: [X] GREEN [ ] OTHER

[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG

[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE

[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:

[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3

[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.

PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:

MICROSECTION: [ ] YES

BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE

[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE

[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE

[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design

DESIGNED FOR: TI Internal

FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE

LAYER NAME = [redacted]Bottom

PLOT NAME = M2 Board Dimensions

BOARD #: Robotics Design REV: A SVN REV: Not in version control

SID #: TIDA-060054

GENERATED : 10/26/2026 9:53:47 PM

TEXAS INSTRUMENTS

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ENGINEER: Garret Godfrey

LAYOUT BY: Tessolve

SCALE: 0.72

ALTIUM DESIGNER VERSION: 23.1.1.15

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

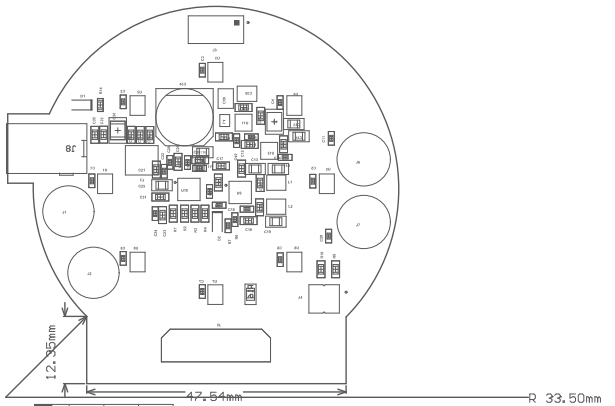
STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.
2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.
3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED .
PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA
TENTING / COVERING " REQUIREMENTS.
4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE
WITH COPPER, SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.685 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = [redacted]Bottom
PLOT NAME = M3.3D-STEP.Top

BOARD #: Robotics Design REV: A SVN REV: Not in version control
3RD NOTTED NOTT EDROP SUM
3D #: TIDA-060054
GENERATED : 10/26/2026 9:53:48 PM
TEXAS INSTRUMENTS

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221 ■ Install shield to silkscreened box after final wash. Test shall be 5 pt box. Test shall be per the Label Table in the PDF schematic.

222 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

223 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

224 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

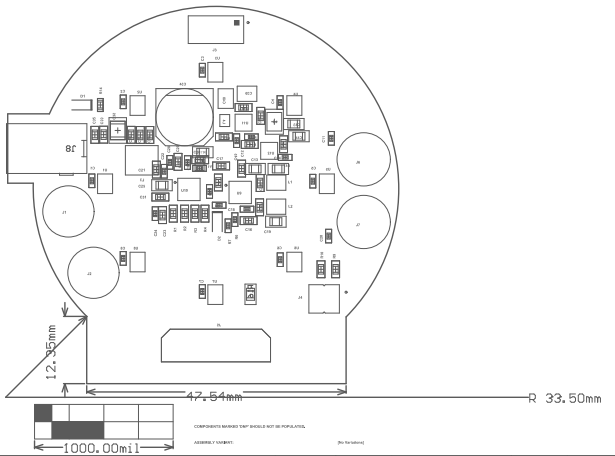
FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.

2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.

3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED .
PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA
TENTING / COVERING " REQUIREMENTS.

4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE
WITH COPPER. SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

JUSTIFICATION FOR CLOSURE "WHO" DOWNGRADE/OVERRIDDEN

(unselected / off) TRANSIENT SUSCEPTIBILITY

DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.685 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = [redacted]Bottom
PLOT NAME = M4 3D STEP Bottom

BOARD #: Robotics Design REV: A SVN REV: Not in version control
SID #: TIDA-060054
GENERATED : 10/26/2026 9:53:49 PM
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ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

221	Board sized to allow normal loss after final mech. Test shall be 5 pt here. Test shall be per the Label Table in the PDF schematic.
222	These assemblies are ESD sensitive, ESD precautions shall be observed.
223	These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
224	These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

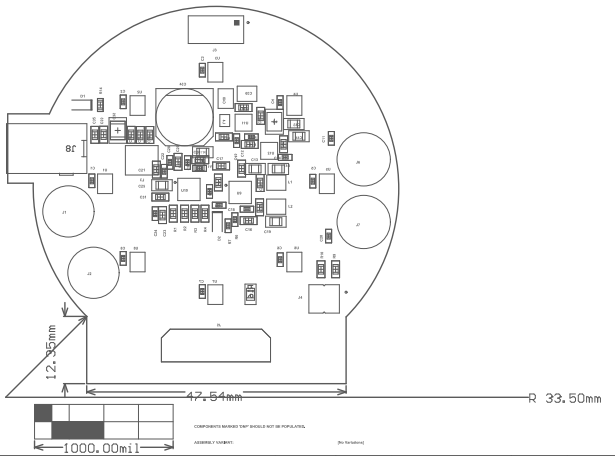
STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.
2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.
3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED .
PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA
TENTING / COVERING " REQUIREMENTS.
4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE
WITH COPPER. SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.

DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.685 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = [redacted]Bottom
PLOT NAME = M5 Assembly Top

BOARD #: Robotics Design REV: A SVN REV: Not in version control
STD #: TIDA-060054
GENERATED : 10/26/2026 9:53:51 PM
TEXAS INSTRUMENTS

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ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

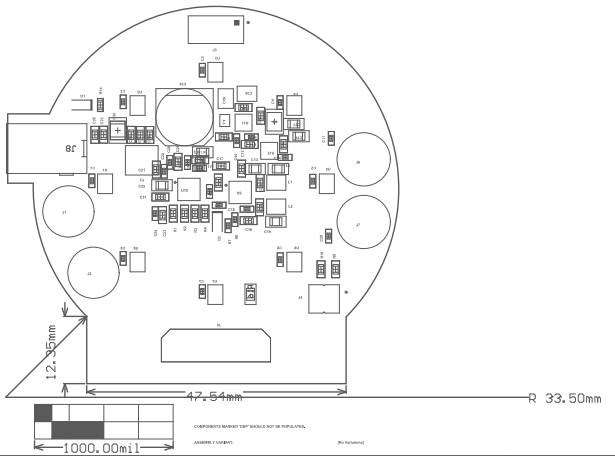
STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.
2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.
3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED .
PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA
TENTING / COVERING " REQUIREMENTS.
4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE
WITH COPPER, SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.685 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = [redacted]Bottom
PLOT NAME = M6 Assembly Bottom
BOARD #: Robotics Design REV: A SVN REV: Not in version control
SID #: TIDA-060054
GENERATED : 10/26/2026 9:53:52 PM
TEXAS INSTRUMENTS

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221 ■ Install shall be silkscreened face after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

222 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

223 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

224 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

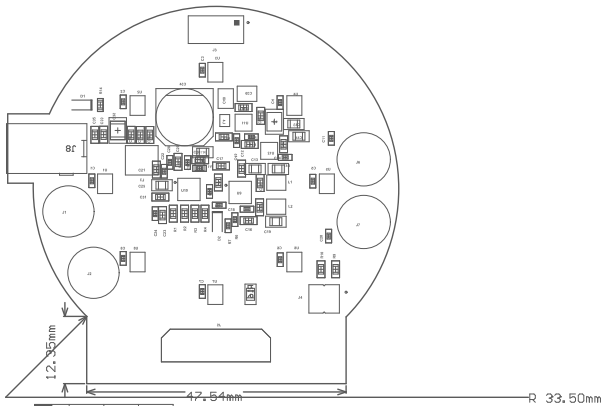
FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.

2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.

3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED .
PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA
TENTING / COVERING " REQUIREMENTS.

4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE
WITH COPPER, SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.

DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.685 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = [redacted]Bottom
PLOT NAME = Mb Title Sheet

BOARD #: Robotics Design REV: A SVN REV: Not in version control
BID #: TIDA-060054
GENERATED : 10/26/2026 9:53:53 PM
TEXAS INSTRUMENTS

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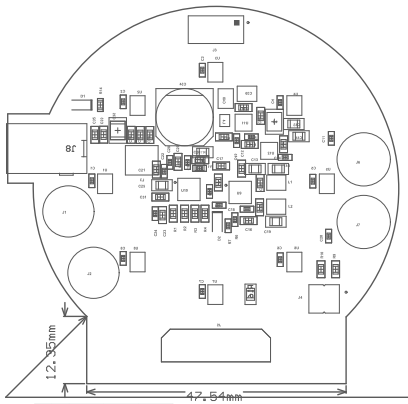
ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

221 ■ Board sized to silkscreened box after final mods. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

222 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

223 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

224 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.

2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.

3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1) AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED . PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA TENTING / COVERING " REQUIREMENTS.

4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE WITH COPPER, SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES . MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.

DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL

MIN. CLEARANCE: 6 MIL

MIN. VIA PAD SIZE: 19.685 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

[X] FR-4 [ ] FR-4 High Tg [ ] OTHER

THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up

TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:

REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES

PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:

SILKSCREEN: [X] TOP [X] BOTTOM

SILKSCREEN COLOR: [X] WHITE [ ] OTHER

SOLDER RESIST COLOR: [X] GREEN [ ] OTHER

[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG

[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE

[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:

[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3

[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.

PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:

MICROSECTION: [ ] YES

BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE

[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE

[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE

[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design

DESIGNED FOR: TI Internal

FILE NAME: Robotics_Design.PcbDoc

ENGINEER: Garret Godfrey

LAYOUT BY: Tessolve

SCALE: 0.72

ALTIUM DESIGNER VERSION: 23.1.1.15

ALL ARTWORK VIEWED FROM TOP SIDE

LAYER NAME = [redacted]Bottom

PLOT NAME = M10 Fab Notes

BOARD #: Robotics Design REV: A SVN REV: Not in version control

IID #: TIDA-060054

GENERATED : 10/26/2026 9:53:54 PM

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IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

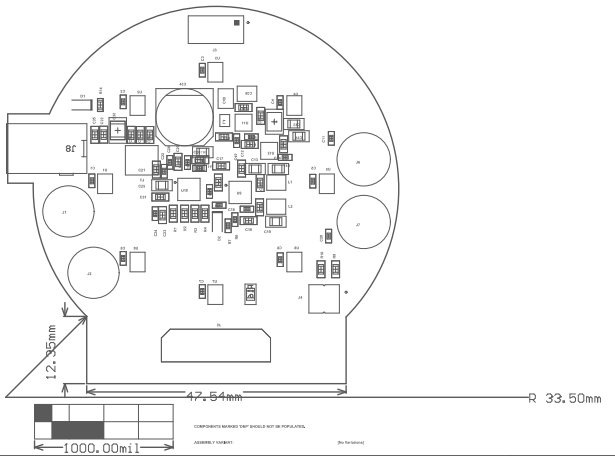
STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.
2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.
3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED .
PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA
TENTING / COVERING " REQUIREMENTS.
4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE
WITH COPPER. SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.685 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = [redacted]Bottom
PLOT NAME = Mid_GerberInformation

BOARD #: Robotics_Design REV: A SVN REV: Not in version control
SID #: TIDA-060054
GENERATED : 10/26/2026 9:53:56 PM
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ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

221 ■ Install shield to silkscreened box after final wash. Test shall be 5 pt box. Test shall be per the Label Table in the PDF schematic.

222 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

223 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

224 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

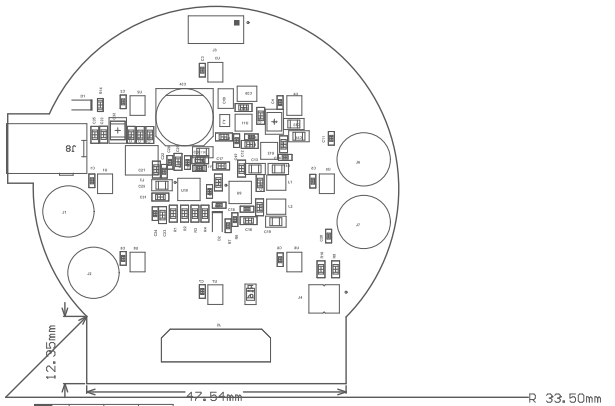
FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.

2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.

3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED .
PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA
TENTING / COVERING " REQUIREMENTS.

4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE
WITH COPPER. SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

JUSTIFICATION FOR TOP CLOCKS "AND" DOWNARD STEPPING

DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.685 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = [redacted]Bottom
PLOT NAME = M12 Stackup

BOARD #: Robotics Design REV: A SVN REV: Not in version control
IID #: TIDA-060054
GENERATED : 10/26/2026 9:53:56 PM TEXAS INSTRUMENTS

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ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

221 ■ Install shield to silkscreened box after final wash. Test shall be 5 pt box. Test shall be per the Label Table in the PDF schematic.

222 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

223 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

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IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

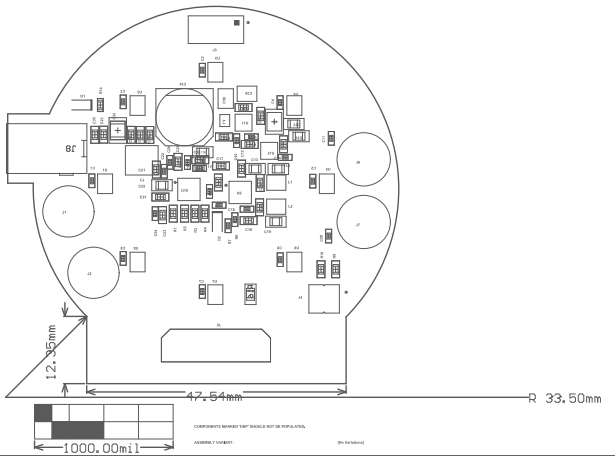
FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.

2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.

3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1) AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED . PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA TENTING / COVERING " REQUIREMENTS.

4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE WITH COPPER, SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES . MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

SOLDERMASK SHALL BE TOP CLOSURE "PRE-TENTED" ETCHED/PRINTED

[overcoat/ref. off]

TRANSKY TUBE/BOX

DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL

MIN. CLEARANCE: 6 MIL

MIN. VIA PAD SIZE: 19.685 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

[X] FR-4 [ ] FR-4 High Tg [ ] OTHER

THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up

TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:

REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES

PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:

SILKSCREEN: [X] TOP [X] BOTTOM

SILKSCREEN COLOR: [X] WHITE [ ] OTHER

SOLDER RESIST COLOR: [X] GREEN [ ] OTHER

[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG

[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE

[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:

[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3

[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.

PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:

MICROSECTION: [ ] YES

BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE

[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE

[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE

[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design

DESIGNED FOR: TI Internal

FILE NAME: Robotics_Design.PcbDoc

ENGINEER: Garret Godfrey

LAYOUT BY: Tessolve

SCALE: 0.72

ALTIUM DESIGNER VERSION: 23.1.1.15

ALL ARTWORK VIEWED FROM TOP SIDE

LAYER NAME = [redacted]Bottom

PLOT NAME = M13 Component Bodies Top

BOARD #: Robotics Design REV: A SVN REV: Not in version control

SID #: TIDA-060054

GENERATED : 10/26/2026 9:53:58 PM

TEXAS INSTRUMENTS

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IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

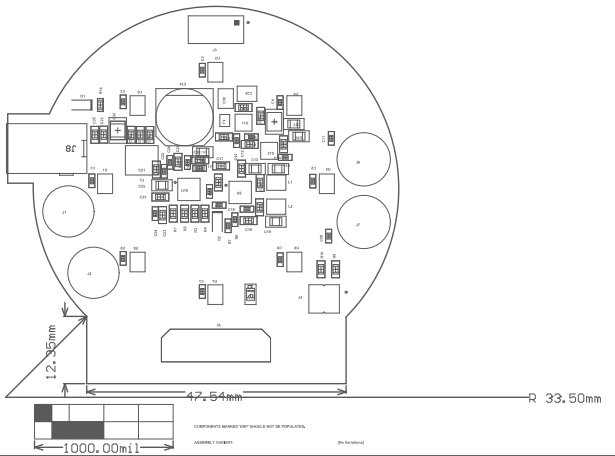
STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.
2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.
3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED .
PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA
TENTING / COVERING " REQUIREMENTS.
4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE
WITH COPPER, SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.685 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = [redacted]Bottom
PLOT NAME = M14 Component Bodies Bottom

BOARD #: Robotics Design REV: A SVN REV: Not in version control
SID #: TIDA-060054
GENERATED : 10/26/2026 9:53:09 PM
TEXAS INSTRUMENTS

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ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

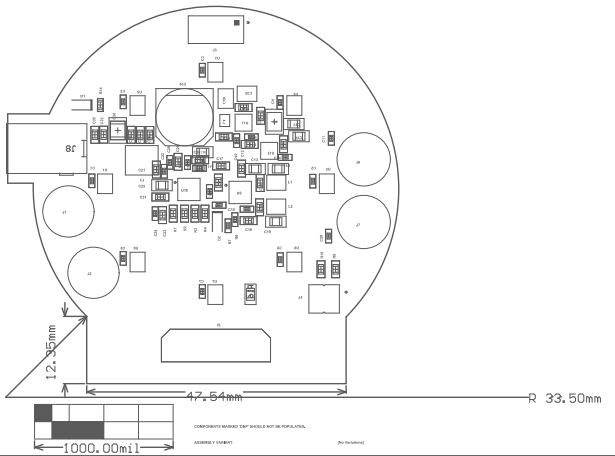
STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.
2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.
3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED .
PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA
TENTING / COVERING " REQUIREMENTS.
4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE
WITH COPPER. SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.685 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = [redacted]Bottom
PLOT NAME = M4S Courtyards Top
BOARD #: Robotics_Design REV: A SVN REV: Not in version control
SID #: TIDA-060054
GENERATED : 10/26/2026 9:54:00 PM
TEXAS INSTRUMENTS

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221 ■ Board sized to silkscreened box after final mask. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

222 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

223 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

224 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

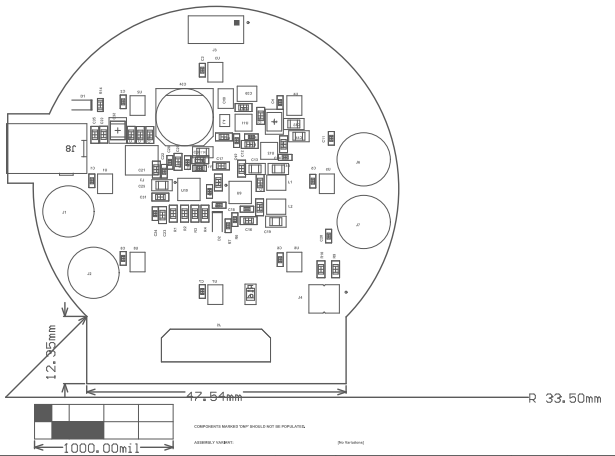
FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.

2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.

3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED .
PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA
TENTING / COVERING " REQUIREMENTS.

4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE
WITH COPPER, SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

JUSTIFICATION TOP CLOCKWISE *AND CENTER* OTHERWISE

DESIGN INFORMATION			
MIN. TRACK WIDTH:	5 MIL		
MIN. CLEARANCE:	6 MIL		
MIN. VIA PAD SIZE:	19.685 MIL		
MINIMUM ANNULAR RING	0.05mm (2MIL)	EXTERNAL	
PER	IPC-D-275 CLASS 2 LEVEL C		
REGISTRATION TOLERANCES:	METAL +/- 5 MIL, HOLES	+/- 3 MIL	
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED):		+/- 3 MIL	

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = [redacted]Bottom
PLOT NAME = M16 Courtyards Bottom

BOARD #: Robotics_Design REV: A SVN REV: Not in version control
STD #: TIDA-060054
GENERATED : 10/26/2026 9:54:01 PM TEXAS INSTRUMENTS

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ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

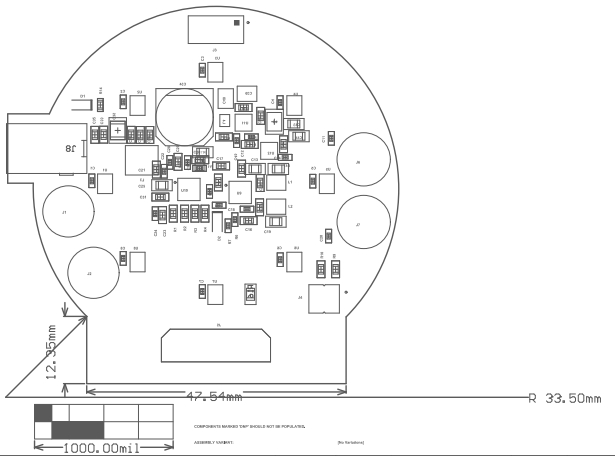
STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
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3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.
2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.
3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED .
PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA
TENTING / COVERING " REQUIREMENTS.
4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE
WITH COPPER. SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.685 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = [redacted]Bottom
PLOT NAME = M17 Embedded Cavity

BOARD #: Robotics_Design REV: A SVN REV: Not in version control
SID #: TIDA-060054
GENERATED : 10/26/2026 9:54:03 PM
TEXAS INSTRUMENTS

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ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

221 ■ Install shield to silkscreened box after final wash. Test shall be 5 pt box. Test shall be per the Label Table in the PDF schematic.

222 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

223 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

224 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

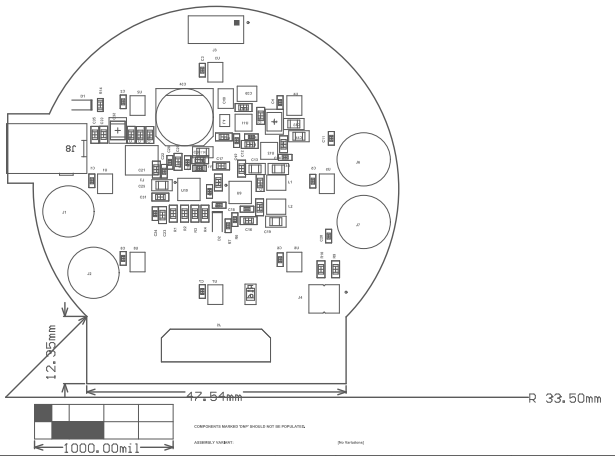
FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.

2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.

3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED .
PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA
TENTING / COVERING " REQUIREMENTS.

4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE
WITH COPPER, SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

JUSTIFICATION FOR CLOSURE "FREE" DEVIATION ENTERED/NEED

DESIGN INFORMATION			
MIN. TRACK WIDTH:	5 MIL		
MIN. CLEARANCE:	6 MIL		
MIN. VIA PAD SIZE:	19.685 MIL		
MINIMUM ANNULAR RING	0.05mm (2MIL)	EXTERNAL	
PER	IPC-D-275 CLASS 2 LEVEL C		
REGISTRATION TOLERANCES:	METAL +/- 5 MIL, HOLES	+/- 3 MIL	
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED):		+/- 3 MIL	

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = [redacted]Bottom
PLOT NAME = M48 Embedded Assembly
BOARD #: Robotics Design REV: A SVN REV: Not in version control
STD #: TIDA-060054
GENERATED : 10/26/2026 9:54:04 PM
TEXAS INSTRUMENTS

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ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

221 ■ Board sized to silkscreened box after final route. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

222 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

223 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

224 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

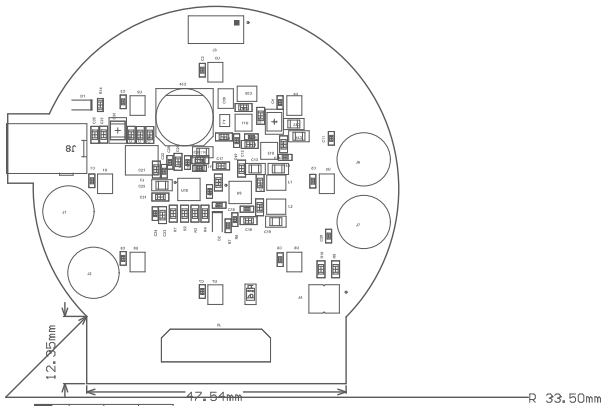
FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.

2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.

3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED .
PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA
TENTING / COVERING " REQUIREMENTS.

4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE
WITH COPPER, SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.

DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.685 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = [redacted]Bottom
PLOT NAME = M40 Embedded Keepout

BOARD #: Robotics_Design REV: A SVN REV: Not in version control
SID #: TIDA-060054
GENERATED : 10/26/2026 9:54:05 PM
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ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

221 ■ Install shield to silkscreened box after final wash. Test shall be 5 pt box. Test shall be per the Label Table in the PDF schematic.
222 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
223 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
224 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

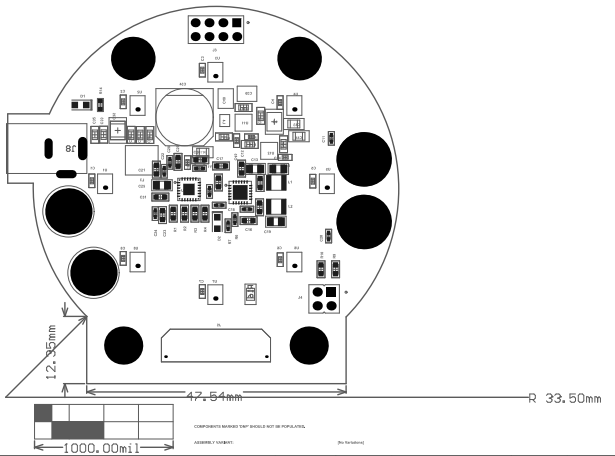
STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.
2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.
3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED .
PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA
TENTING / COVERING " REQUIREMENTS.
4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE
WITH COPPER. SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.

DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.685 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = [redacted]Bottom
PLOT NAME = Top Pad Master

BOARD #: Robotics Design REV: A SVN REV: Not in version control
SID #: TIDA-060054
GENERATED : 10/26/2026 9:54:06 PM
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ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

221 Bevel sized to silkscreened text after final mask. Text shall be 5 pt font. Text shall be per the Label Table in the PDF schematic.

222 These assemblies are ESD sensitive, ESD precautions shall be observed.

223 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

224 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

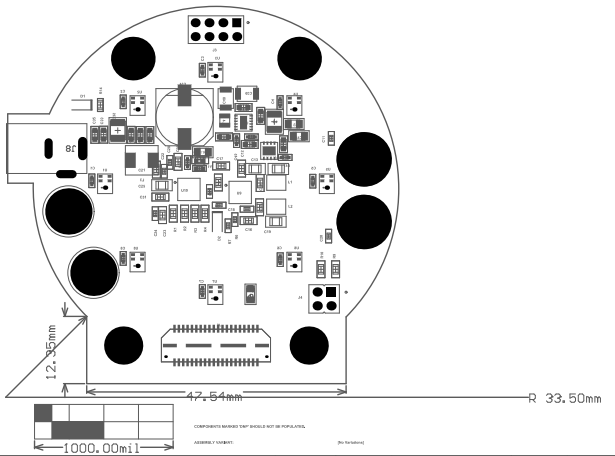
FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.

2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.

3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED .
PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA
TENTING / COVERING " REQUIREMENTS.

4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE
WITH COPPER, SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



1000.00mil

COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

JUSTIFICATION FOR CLOSURE "NOT CONFORMS" ENTERED HERE

DESIGN INFORMATION			
MIN. TRACK WIDTH:	5 MIL		
MIN. CLEARANCE:	6 MIL		
MIN. VIA PAD SIZE:	19.685 MIL		
MINIMUM ANNULAR RING	0.05mm (2MIL)	EXTERNAL	
PER	IPC-D-275 CLASS 2 LEVEL C		
REGISTRATION TOLERANCES:	METAL +/- 5 MIL, HOLES	+/- 3 MIL	
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED):		+/- 3 MIL	

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = [redacted]Bottom
PLOT NAME = Bottom Pad Master
BOARD #: Robotics Design REV: A SVN REV: Not in version control
SID #: TIDA-060054
GENERATED : 10/26/2026 9:54:07 PM
TEXAS INSTRUMENTS

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ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
	Dielectric 1	FR-4	4.60mil	4	
2	L2-GND1	copper	1.40mil		
	Dielectric 2	FR-4	4.00mil	4	
3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

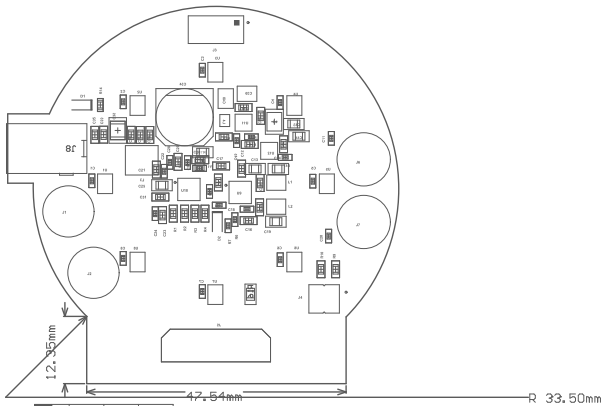
FAB NOTES

1.THIS IS IMPEDANCE CONTROLLED BOARD.

2.ALL VIAS ARE TENTED IN BOTH SIDE UNLESS OTHERWISE MASK OPENED IN GERBERS.

3.VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1)
AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED .
PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED " VIA
TENTING / COVERING " REQUIREMENTS.

4.7.874 MILS VIAS NEED TO BE FILLED WITH NON CONDUCTIVE EPOXY-RESIN AND OVERPLATE
WITH COPPER, SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDES .
MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.



DESIGN INFORMATION

MIN. TRACK WIDTH: 5 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.685 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = [redacted]Bottom
PLOT NAME = Keep Out Layer
BOARD #: Robotics Design REV: A SVN REV: Not in version control
SID #: TIDA-060054
GENERATED : 10/26/2026 9:54:09 PM
TEXAS INSTRUMENTS

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DRILL TABLE

Symbol	Count	Hole Size	Plated	Hole Type
	13	7.87mil (0.200mm)	PTH	Round
	525	10.00mil (0.254mm)	PTH	Round
	2	29.92mil (0.760mm)	PTH	Slot
	8	31.50mil (0.800mm)	NPTH	Round
	2	39.37mil (1.000mm)	NPTH	Round
	1	39.76mil (1.010mm)	PTH	Slot
	8	40.00mil (1.016mm)	PTH	Round
	4	47.24mil (1.200mm)	PTH	Round
	2	126.00mil (3.200mm)	PTH	Round
	2	129.92mil (3.300mm)	PTH	Round
	2	144.00mil (3.658mm)	PTH	Round
	2	214.57mil (5.450mm)	PTH	Round
	571 Total			

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position,
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

FOR 7.87 MIL DRILL +0/-7.87MIL

FOR 10 MIL DRILL +0/-10 MIL

FOR NPTH +/-2MIL

FOR PTH +/-3MIL

IMPEDANCE TABLE:

LAYERS	50 OHM SIGNAL +/- 10% Tolerance	
	TRACE WIDTH	REFERENCE
L1	6.5 MILLS	L2
L3	5 MILLS	L2&L4
L6	6.5 MILLS	L5

STACK UP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.20mil	3.5	
1	L1_TOP	Copper	1.20mil		
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2	L2-GND1	copper	1.40mil		
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3	L3_Signal	copper	1.40mil		
	Dielectric 3	FR-4	39.20mil	4	
4	L4_GND2	copper	1.40mil		
	Dielectric 4	FR-4	4.00mil	4	
5	L5_PWR	copper	1.40mil		
	Dielectric 5	FR-4	4.60mil	4	
6	L6_Bottom	Copper	1.20mil		
	Bottom Solder	Solder Resist	1.20mil	3.5	
	Bottom Overlay				

Total board thickness: 68.00mil +/-10%

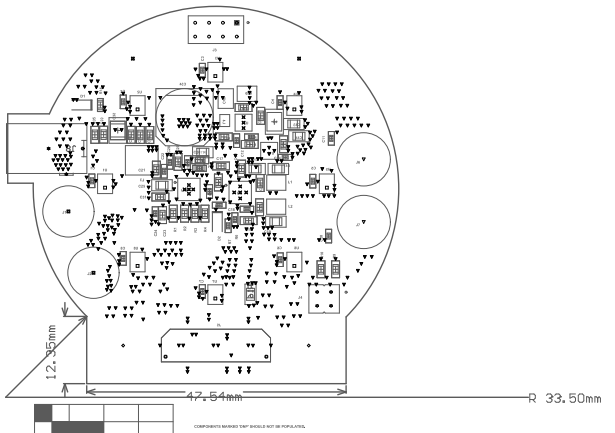
FAB NOTES

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REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
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MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER Refer stack up
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
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DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
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TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = Drill Drawing For (L1_TOP • L6_Bottom)
PLOT NAME = Drill Drawing For (L1_TOP • L6_Bottom)

BOARD #: Robotics_Design REV: A SVN REV: Not in version control
SID #: TIDA-060054
GENERATED : 10/26/2026 9:54:10 PM

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ENGINEER: Garret Godfrey
LAYOUT BY: Tessolve
SCALE: 0.72
ALTIUM DESIGNER VERSION: 23.1.1.15

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Total board thickness: 68.00mil +/-10%

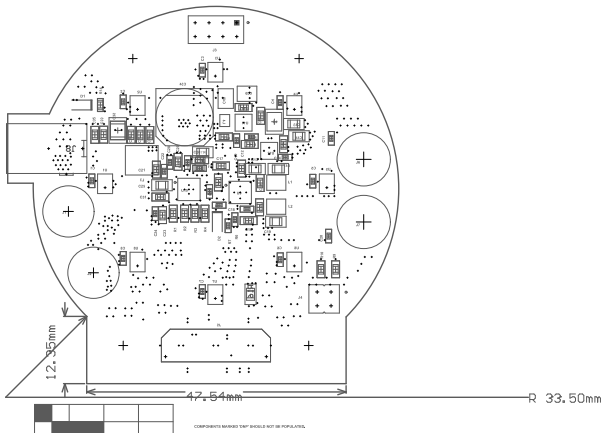
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BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
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SILKSCREEN COLOR: [X] WHITE [ ] OTHER
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TEXAS INSTRUMENTS

PROJECT TITLE: Robotics Design
DESIGNED FOR: TI Internal
FILE NAME: Robotics_Design.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = [illegible]Bottom
PLOT NAME = Drill Guide For (L1_TOP - L6_Bottom)

BOARD #: Robotics Design REV: A SVN REV: Not in version control
3RD #: TIDA-060054
GENERATED : 10/26/2026 9:54:41 PM

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LAYOUT BY: Tessolve
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